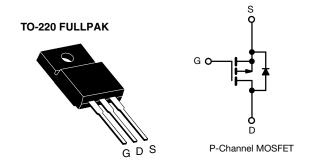


www.vishay.com

Vishay Siliconix

Power MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	-60			
$R_{DS(on)}(\Omega)$	$V_{GS} = -10 \text{ V}$	0.14		
Q _g max. (nC)	34			
Q _{gs} (nC)	9.9			
Q _{gd} (nC)	16			
Configuration	Single			



FEATURES

- Isolated package
- High voltage isolation = 2.5 kV_{RMS} (t = 60 s; f = 60 Hz



Sink to lead creepage distance = 4.8 mm

- P-channel
- 175 °C operating temperature
- Dynamic dV/dt rating
- Low thermal resistance
- · Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

Note

This datasheet provides information about parts that are RoHS-compliant and / or parts that are non-RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details.

DESCRIPTION

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance cost-effectiveness.

The TO-220 FULLPAK eliminates the need for additional insulating hardware in commercial-industrial applications. The molding compound used provides a high isolation capability and a low thermal resistance between the tab and external heatsink. This isolation is equivalent to using a 100 micron mica barrier with standard TO-220 product. The FULLPAK is mounted to a heatsink using a single clip or by a single screw fixing.

ORDERING INFORMATION			
Package	TO-220 FULLPAK		
Lead (Pb)-free	IRFI9Z34GPbF		
	SiHFI9Z34G-E3		
SnPb	IRFI9Z34G		
	SiHFI9Z34G		

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V _{DS}	-60	V	
Gate-Source Voltage			V_{GS}	± 20		
Continuous Drain Current	V _{GS} at -10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$	I _D	-12		
		T _C = 100 °C		-8.5	Α	
Pulsed Drain Current ^a			I _{DM}	-48		
Linear Derating Factor				0.28	W/°C	
Single Pulse Avalanche Energy ^b			E _{AS}	370	mJ	
Repetitive Avalanche Current ^a			I _{AR}	-12	А	
Repetitive Avalanche Energy a			E _{AR}	4.2	mJ	
Maximum Power Dissipation	T _C =	25 °C	P_{D}	42	W	
Peak Diode Recovery dV/dt c			dV/dt	-4.5	V/ns	
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +175	°C	
Soldering Recommendations (Peak temperature) d	for 10 s			300	7	
Mounting Torque	6-32 or M3 screw			10	lbf ⋅ in	
				1.1	N⋅m	

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11). b. $V_{DD}=$ -25 V, starting $T_J=$ 25 °C, L = 3.0 mH, $R_G=$ 25 Ω , $I_{AS}=$ -12 A (see fig. 12). c. $I_{SD}\leq$ -12 A, dl/dt \leq 170 A/µs, $V_{DD}\leq$ V_{DS} , $T_J\leq$ 175 °C. d. 1.6 mm from case.

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THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R _{thJA}	-	65	°C/W	
Maximum Junction-to-Case (Drain)	R _{thJC}	-	3.6	G/VV	

PARAMETER	SYMBOL	TES	TEST CONDITIONS		TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$		-60	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference to 25 °C, I _D = -1 mA		-	-0.060	-	V/°C
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	-2.0	-	-4.0	V
Gate-Source Leakage	I _{GSS}		$V_{GS} = \pm 20 \text{ V}$		-	± 100	nA
Zava Cata Valtaga Dvain Curvent		V _{DS} =	$V_{DS} = -60 \text{ V}, V_{GS} = 0 \text{ V}$		-	-100	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -48 \text{ V}$	', V _{GS} = 0 V, T _J = 150 °C	-	-	-500	μA
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = -10 V	I _D = -7.2 A ^b	-	-	0.14	Ω
Forward Transconductance	9 _{fs}	V _{DS} =	-25 V, I _D = -7.2 A ^b	5.4	-		S
Dynamic							
Input Capacitance	C _{iss}	$V_{GS} = 0 \text{ V},$ $V_{DS} = -25 \text{ V},$ $f = 1.0 \text{ MHz}, \text{ see fig. 5}$ $f = 1.0 \text{ MHz}$		-	1100	-	- pF
Output Capacitance	C _{oss}			-	620	-	
Reverse Transfer Capacitance	C _{rss}			-	100		
Drain to Sink Capacitance	С			-	12		
Total Gate Charge	Qg			-	-	34	nC
Gate-Source Charge	Q _{gs}	V _{GS} = -10 V	I _D = -18 A, V _{DS} = -48 V, see fig. 6 and 13 ^b	-	-	9.9	
Gate-Drain Charge	Q _{gd}		See lig. 0 and 15	-	-	16	
Turn-On Delay Time	t _{d(on)}			-	18		
Rise Time	t _r		$V_{DD} = -30 \text{ V}, I_D = -18 \text{ A},$		120		ns
Turn-Off Delay Time	t _{d(off)}	R_G = 12 Ω , R_D = 1.5 Ω , see fig. 10 b		-	20	-	
Fall Time	t _f			-	58	-	
Internal Drain Inductance	L_D	6 mm (0.25")	Between lead, 6 mm (0.25") from package and center of die contact		4.5	-	- nH
Internal Source Inductance	L _S				7.5	-	
Gate Input Resistance	Rg	f = 1 MHz, open drain		0.7	-	3.9	Ω
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p -n junction diode		-	-	-12	^
Pulsed Diode Forward Current ^a	I _{SM}			-	-	-48	- A
Body Diode Voltage	V _{SD}	T _J = 25 °C, I _S = -12 A, V _{GS} = 0 V b		-	-	-6.3	V
Body Diode Reverse Recovery Time	t _{rr}	$T_J = 25 ^{\circ}\text{C}, I_F = -18 \text{A}, \text{dI/dt} = 100 \text{A/}\mu\text{s}^{\text{b}}$		-	100	200	ns
Body Diode Reverse Recovery Charge	Q _{rr}			-	0.28	0.52	μC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L _S and				L _D)	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width \leq 300 μ s; duty cycle \leq 2 %.



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

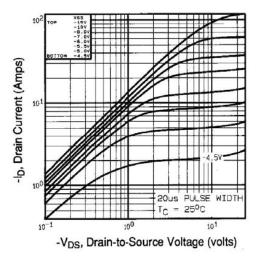


Fig. 1 - Typical Output Characteristics, T_C= 25 °C

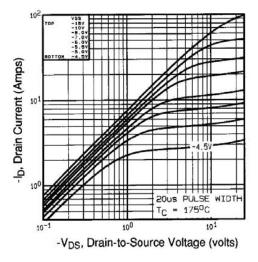


Fig. 2 - Typical Output Characteristics, T_C= 175 °C

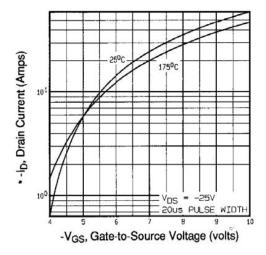


Fig. 3 - Typical Transfer Characteristics

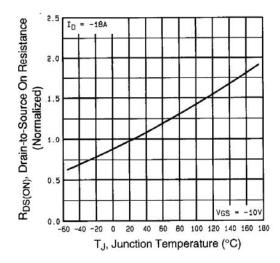


Fig. 4 - Normalized On-Resistance vs. Temperature



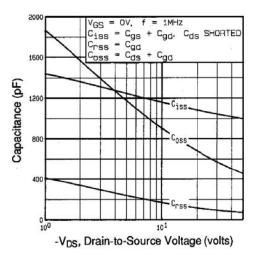


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

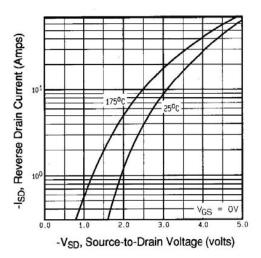


Fig. 7 - Typical Source-Drain Diode Forward Voltage

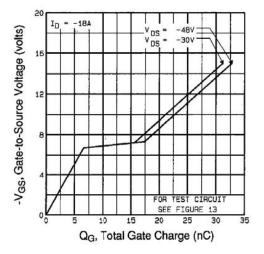


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

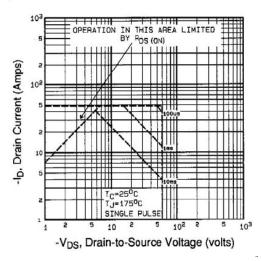


Fig. 8 - Maximum Safe Operating Area



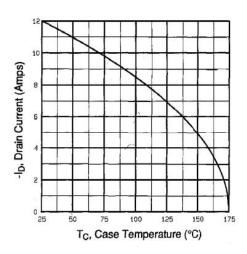


Fig. 9 - Maximum Drain Current vs. Case Temperature

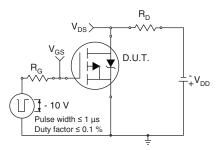


Fig. 10a - Switching Time Test Circuit

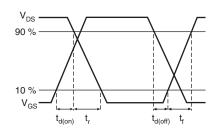


Fig. 10b - Switching Time Waveforms

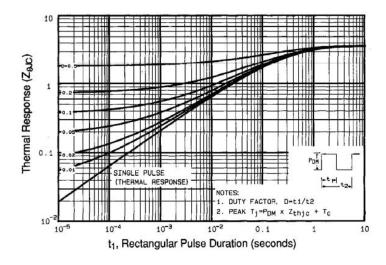


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

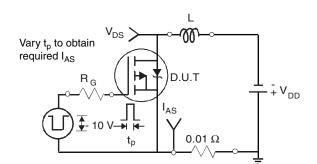


Fig. 12a - Unclamped Inductive Test Circuit

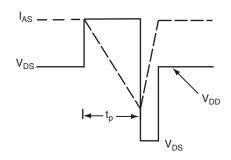


Fig. 12b - Unclamped Inductive Waveforms



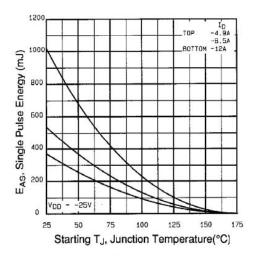


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

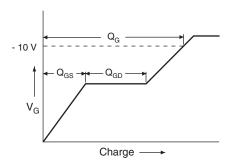


Fig. 13a - Basic Gate Charge Waveform

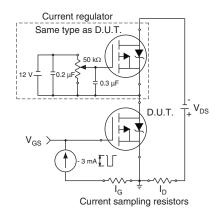
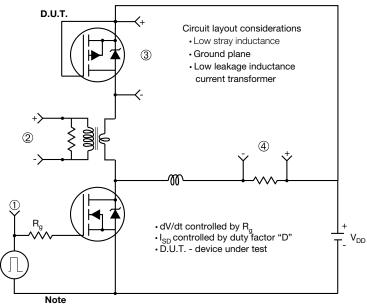


Fig. 13b - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



· Compliment N-Channel of D.U.T. for driver

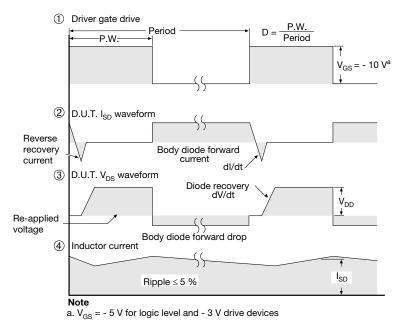


Fig. 14 - For P-Channel

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